Appln. No.: 10/600,312

Amendment Dated: June 29, 2004 Reply to Office Action of: May 11, 2004

## **Amendments to the Specification:**

Please replace the sentence, beginning before the first line on page 1, with the following rewritten sentence:

This application is a divisional of U.S. Patent Application No. 09/907,188, filed July 17, 2001, which has issued a U.S. Patent No. 6,609,458 on August 26, 2003.

Please replace the sentence, beginning before the title Detailed Description of the Invention on page 4, with the following rewritten sentence:

The entire disclosure of U.S. Patent Application No. 09/907,188, filed July 17, 2001, which has issued a U.S. Patent No. 6,609,458 on August 26, 2003, is expressly incorporated by reference herein.

Please replace the paragraph, beginning at page 10, line 27, with the following rewritten paragraph:

When patterpattern hole 12a is filled excessively with cream solder 9 as shown in Fig. 10B, surplus cream solder 9 overflows pattern hole 12a. In this case, measuring line Lb reflects the surface of solder 9 and becomes different from the normal height h0.